

Integrated photonics for quantum: when every photon counts

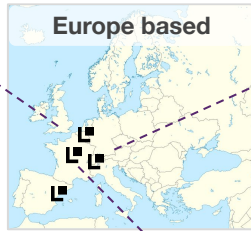
Anton Stroganov
2025

European PIC manufacturing company with a global reach

LIGENTEC key facts



Ghent, Belgium



Europe based



LIGENTEC HQ , Lausanne, Switzerland



Global Reach

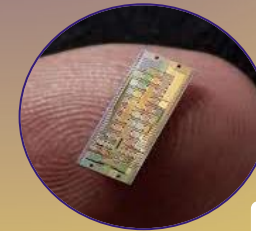
Team of 70+ photonic enthusiasts



Corbeil, France

Best-in-class Silicon Nitride integrated photonic circuits

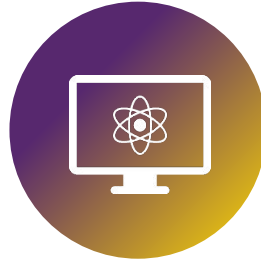
- Low Loss SiN
(down to < 1 dB/m)
- 3+ technology platforms
(AN150, AN350, AN800)
- Integration with actives
- Extensive PDK



We are proud to serve leading companies and research institutions in many different domains



LIDAR



QUANTUM



**SPACE &
DEFENSE**

MORE APPLICATION AREAS



**BIOSENSING
& MICROSCOPY**



SENSORS



**TELECOM &
DATACOM**



**NEUROMORPHIC
COMPUTING**



**AUGMENTED
REALITY**



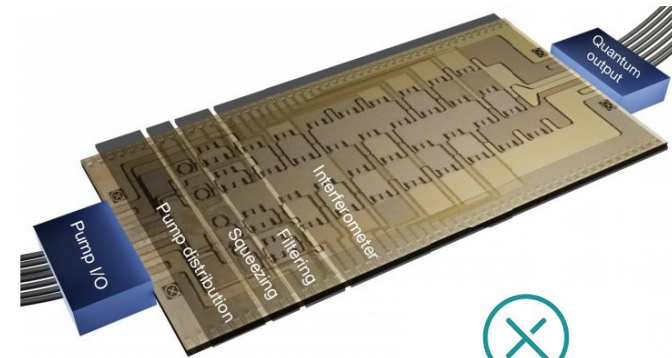
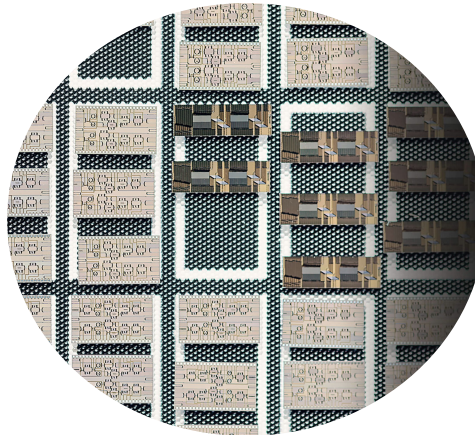
METROLOGY

Applications - Quantum

Showcase: Quantum Computing

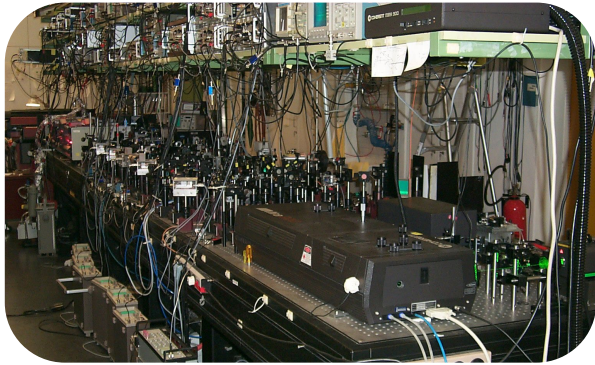


Our chips served as key part of a photonic quantum computer to generate and manipulate quantum states



Photonic Quantum Computer with Ligentec PICs

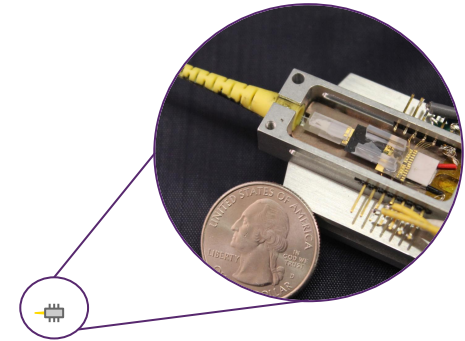
Potential of Photonic Integration



Year 1998, ~several m³



Year 2008, ~1 m³ MenloSystems



Year 2020, ~1 cm³



Why Photonic Integration?

Why in the scope of quantum?

Miniaturization: size, weight, power

Lowering complexity: no discrete (moving) parts

Scalability and cost

Introduction

Potential of Photonic Integration - Quantum computing

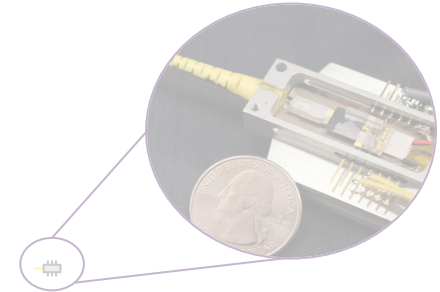


Year 1998, ~several m³

MAX-PLANCK-INSTITUTE
OF QUANTUM OPTICS
GARCHING



Year 2008, ~1 m³ MenloSystems

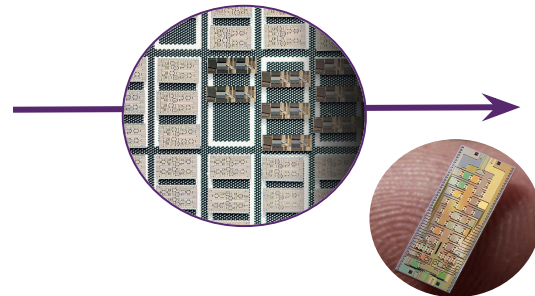


Year 2020, ~1 cm³



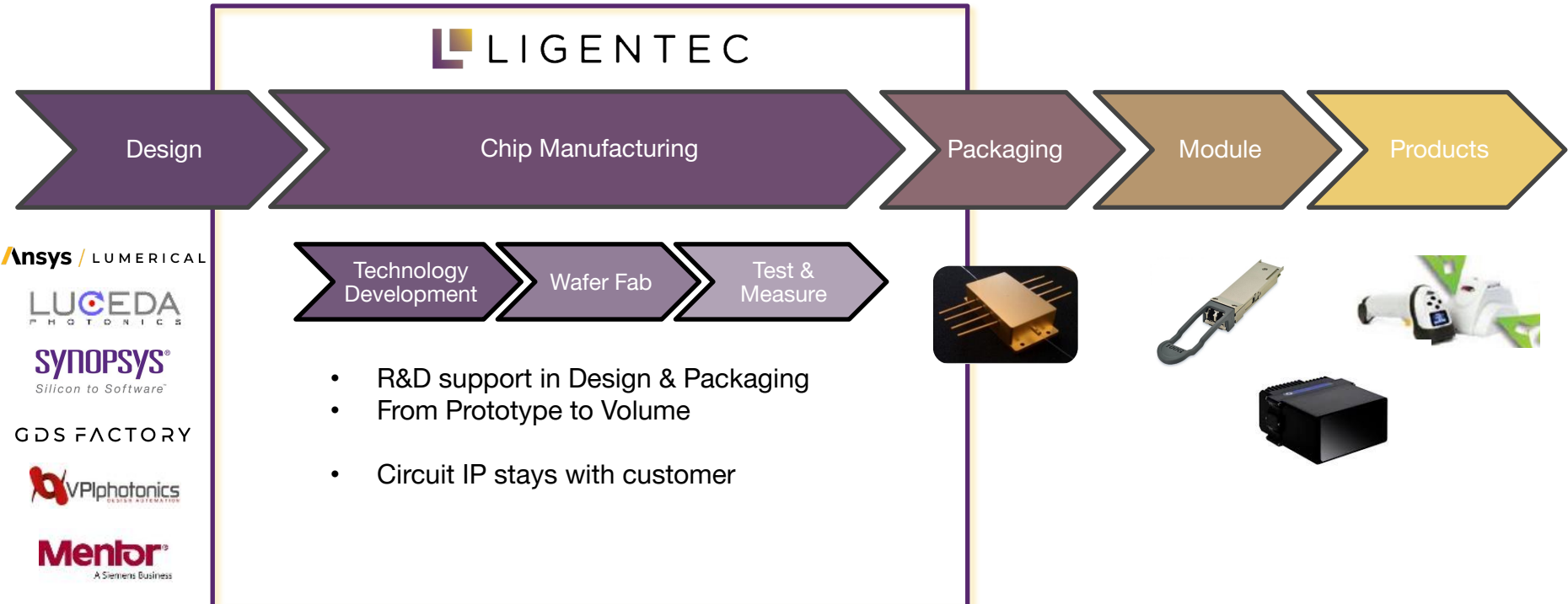
Year 2021, ~several m³

IEEE Spectrum



?

LIGEN TEC is photonic integrated circuits manufacturing provider with mature scalable technology and strong well-established network of partners within the photonic ecosystem



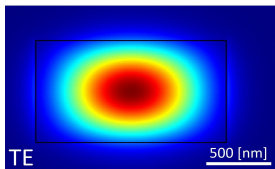
Mature and versatile platform with modular approach and unique expertise in thick films

SiN as a material:

Si Photonics
+
Wide Transparency (400-3500nm)
High power handling (no TPA)
Higher thermal stability
Lower Loss

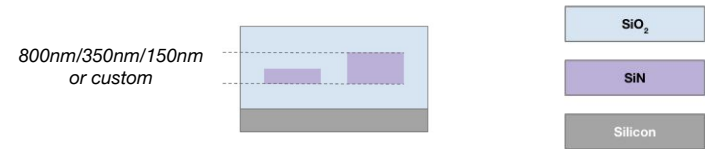
Thick SiN platform:

High confinement waveguides

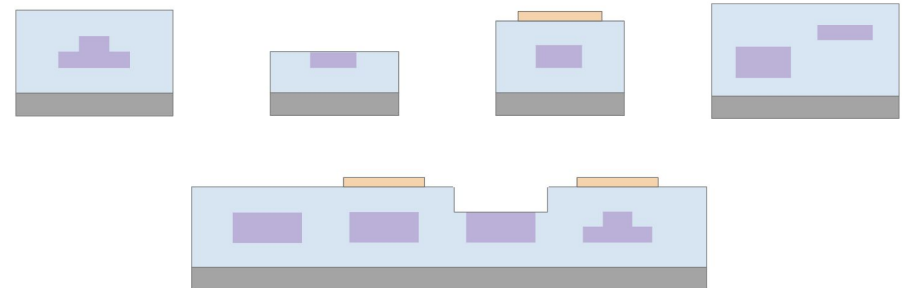


Very low loss
(down to <1 dB/m)
Small footprint
+
Dispersion Engineering
Access to nonlinear effects

Basic Process: SiN waveguides



+ Cross-compatible modules:



+ Extensive PDK and component library

Integrated Photonics for Quantum Computing

nature

<https://doi.org/10.1038/s41586-025-08820-7>

Accelerated Article Preview

A manufacturable platform for photonic quantum computing

Received: 30 July 2024

PsiQuantum Team

Accepted: 20 February 2025

Article

Scaling and networking a modular photonic quantum computer

<https://doi.org/10.1038/s41586-024-08406-9>

Received: 25 June 2024

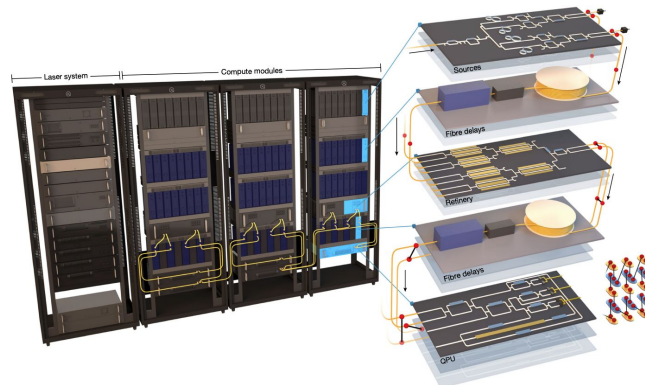
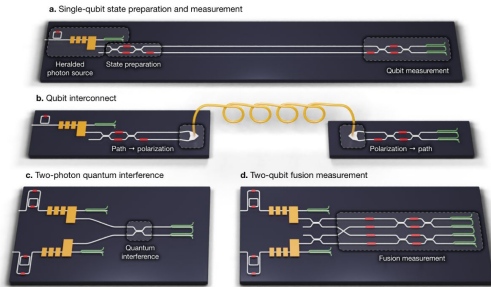
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Open access

Check for updates

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- Low-loss
- Mature process
(but pushing the limits!)
- Scalability
- Modularity
- Efficient interfaces

Further integration:

PD / PNRD

Fast modulators

Amplification

Other

The best of two worlds: two fabs with a different focus

R&D line: Non-Standard *Flexibility and Speed*



Non-standard SiN offering

- Prototyping to mid-volume fabrication of non-standard / development SiN stacks

R&D

- New concepts & technologies

Heterogeneous Integration

- New materials & methods

200 mm line: Standard & Volume *Maturity & Control & Capacity*



Standard SiN offering

- Standard SiN stacks
- MPW runs, Pilot & niche quantities
- High volume production

Automation & Quality

- Highly automated process flow
- Fully automated testing
- IATF 16949 certified / ISO 13485 compliant

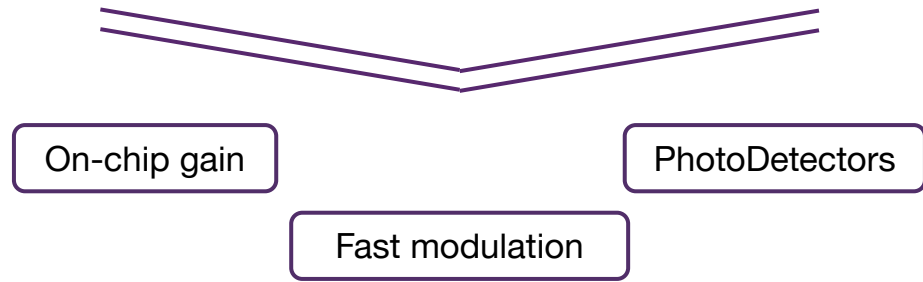
One basis, large diversity in the add-ons

Materials and Functionalities

Many great materials, each with their own merits:

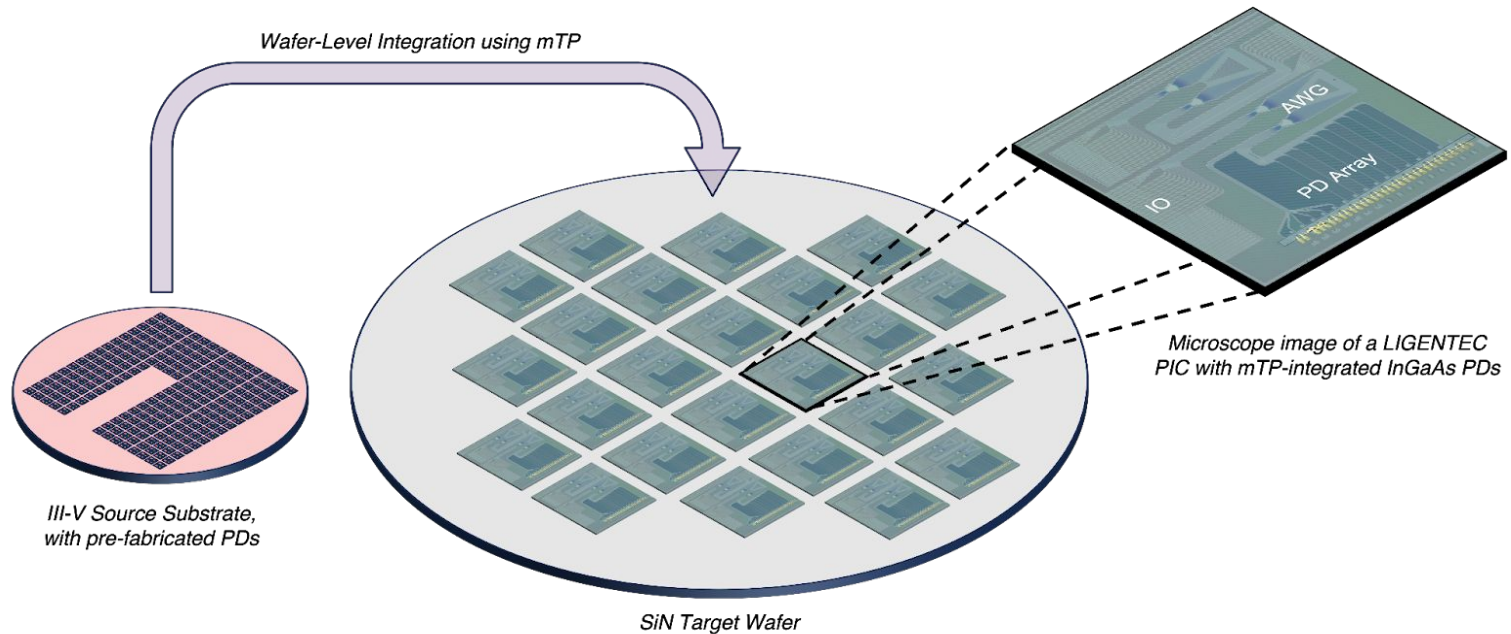


+



Heterogeneous integration of photodiodes

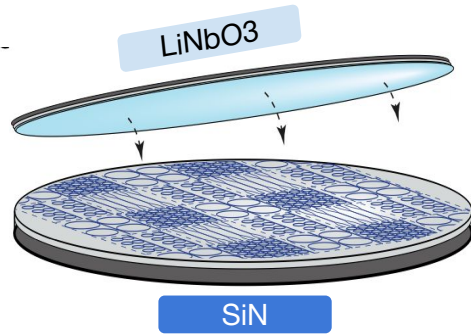
Micro-Transfer Printing: high-throughput wafer-level integration technique



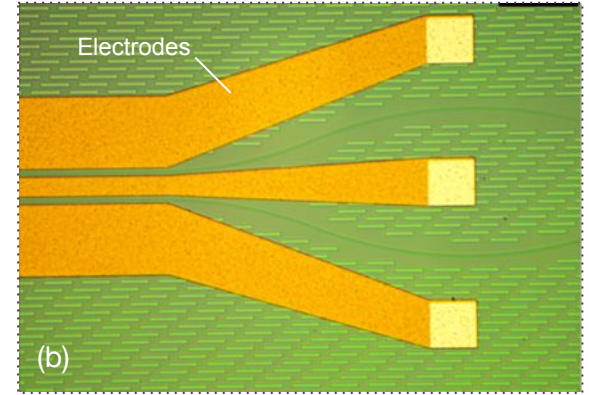
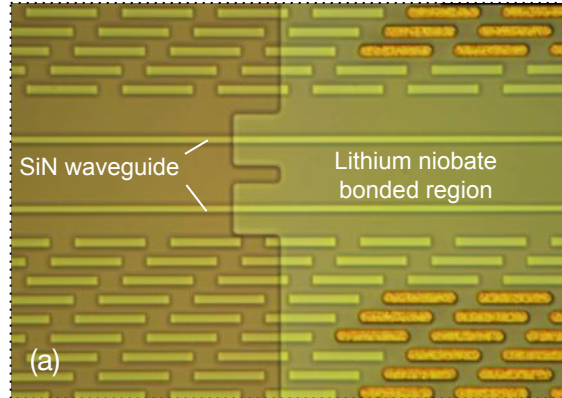


World's first integrated value chain platform initiative for heterogeneous integration in photonics

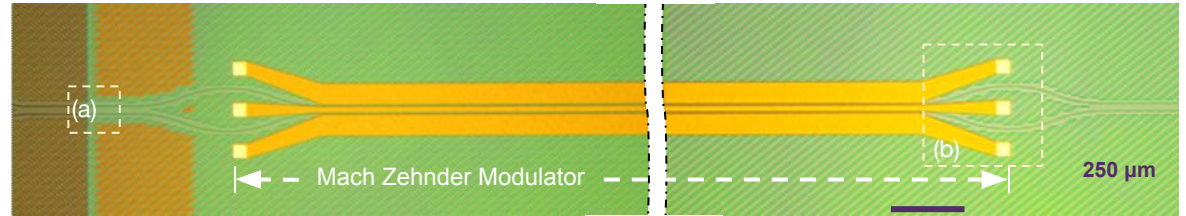
Wafer bonding of thin-film lithium niobate



Churaev et al., Nature Comms (2023)

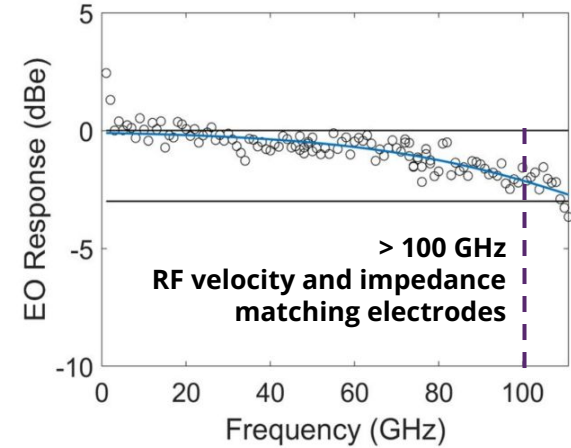
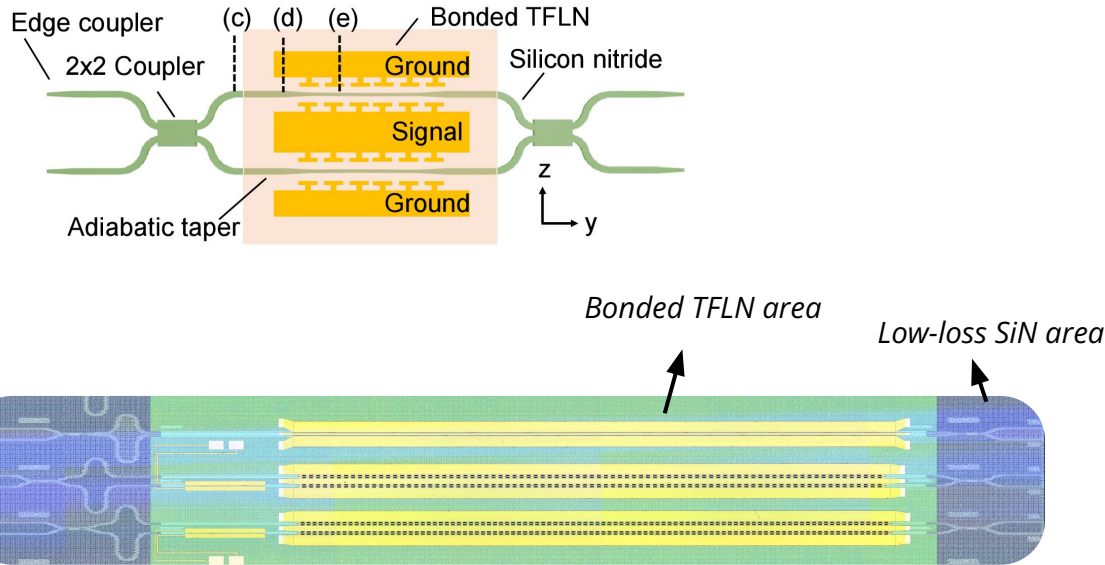


Fast modulators on mature SiN platform.
Scalable, wafer-level approach.



Heterogeneous modulators: achievable results

No extra design complexity; up to **>100 GHz bandwidth demonstrated**



Electro-optic response normalized to 3 GHz
Bandwidth up to **110 GHz** measured
 $V\pi L = 3.4 \text{ V}\cdot\text{cm}$

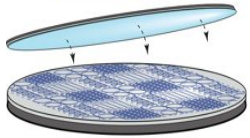
"High-performance Hybrid Lithium Niobate Electro-optic Modulators Integrated with Low-loss Silicon Nitride Waveguides on a Wafer-scale Silicon Photonics Platform".
<https://arxiv.org/abs/2504.00311>



LIGENTEC - European open-access PIC foundry;
Clear path from prototype to volume production



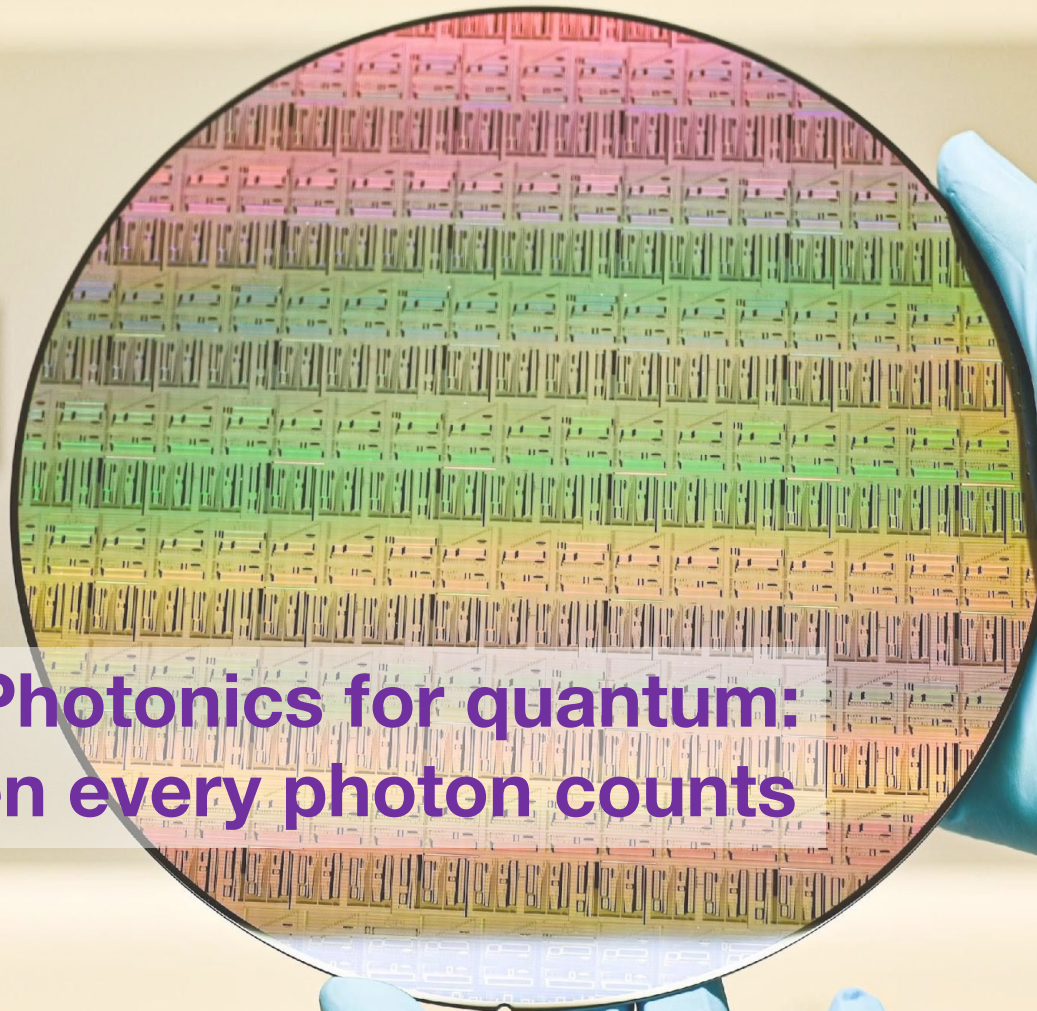
Versatile modular technology for variety of applications;
Visible to Mid-IR wavelength ranges
Quantum Computing, QRNG, QKD, and many more



Activation of low-loss integrated photonics
Scalable heterogeneous integration of fast modulators and photodiodes



Reliable partner at all stages;
Design / Layout / Engineering assistance for your development



Integrated Photonics for quantum: when every photon counts

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2025